



MODEL NO. : G1549HD122GF-001  
ISSUED DATE: 2016-05-27  
VERSION : A0

- Preliminary Specification
- Final Product Specification

Customer : \_\_\_\_\_

Approved by	Notes

GVO Confirmed :

Prepared by	Checked by	Approved by
黄赛博	刘敏	魏朝刚

This technical specification is subjected to change without notice.



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### Record of Revision

Rev	Issue Date	Description	Editor
A0	2016.05.19	Draft	Huang Saibo

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## 1 General Specifications

	Feature	Spec	Remark
<b>Display Spec</b>	Screen Size (inch)	5.49	
	Display Mode	AMOLED	
	Resolution(dot)	720 (W) x RGB x 1280(H)	
	Active Area(mm)	68.40(W)×121.60 (H)	
	Pixel Pitch (um)	95.00(W) x 95.00 (H)	
	Pixel Configuration	V-Style3	
	Technology Type	LTPS	
	Color Depth	16.7M	
	Interface	MIPI 4LANE	
	Surface Treatment	Hard Coating	
<b>Mechanical Characteristics</b>	With TP/Without TP	With TP(on Cell)	
	Module Outline Dimension(W x H x D) (mm)	70.80(W)x128.47(H)x 0.77 (D)	Excluding Cover lens
	Weight (g)	TBD	
<b>Electronic</b>	Driver IC(Type)	RM67120	
	Touch IC(Type)	GT1151	

Note 1: Requirements on Environmental Protection: RoHS.



## 2 Input/output Terminals

### 2.1 Main FPC Pin Assignment

FPC connector: FP270H-039G1AM(JXT)/FP270H-039G10M(Shenzhen Pei Heng),ZIF Connector

No	Symbol	I/O	Description
1	GND	GND	Ground
2	GND	GND	Ground
3	GND	GND	Ground
4	VBAT	POWER	Power Supply for Panel
5	VBAT	POWER	Power Supply for Panel
6	VBAT	POWER	Power Supply for Panel
7	VBAT	POWER	Power Supply for Panel
8	VBAT	POWER	Power Supply for Panel
9	GND	GND	Ground
10	OTPV	POWER	OTP function Pin. Must be left open if it is not used.
11	NC	NC	Not Connected
12	GND	GND	Ground
13	D3P	I	MIPI DSI data.
14	D3N	I	MIPI DSI data.
15	GND	GND	Ground
16	D0P	I/O	MIPI DSI data.
17	D0N	I/O	MIPI DSI data.
18	GND	GND	Ground
19	DKP	I	MIPI DSI data.
20	DKN	I	MIPI DSI data.
21	GND	GND	Ground
22	D1P	I	MIPI DSI data.
23	D1N	I	MIPI DSI data.
24	GND	GND	Ground
25	D2P	I	MIPI DSI data.
26	D2N	I	MIPI DSI data.

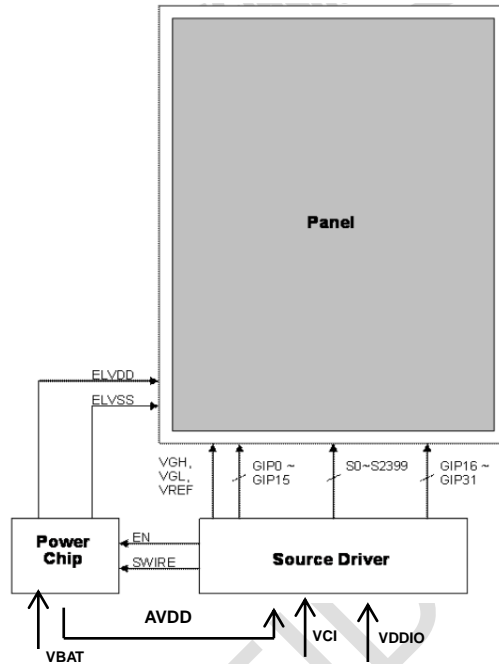
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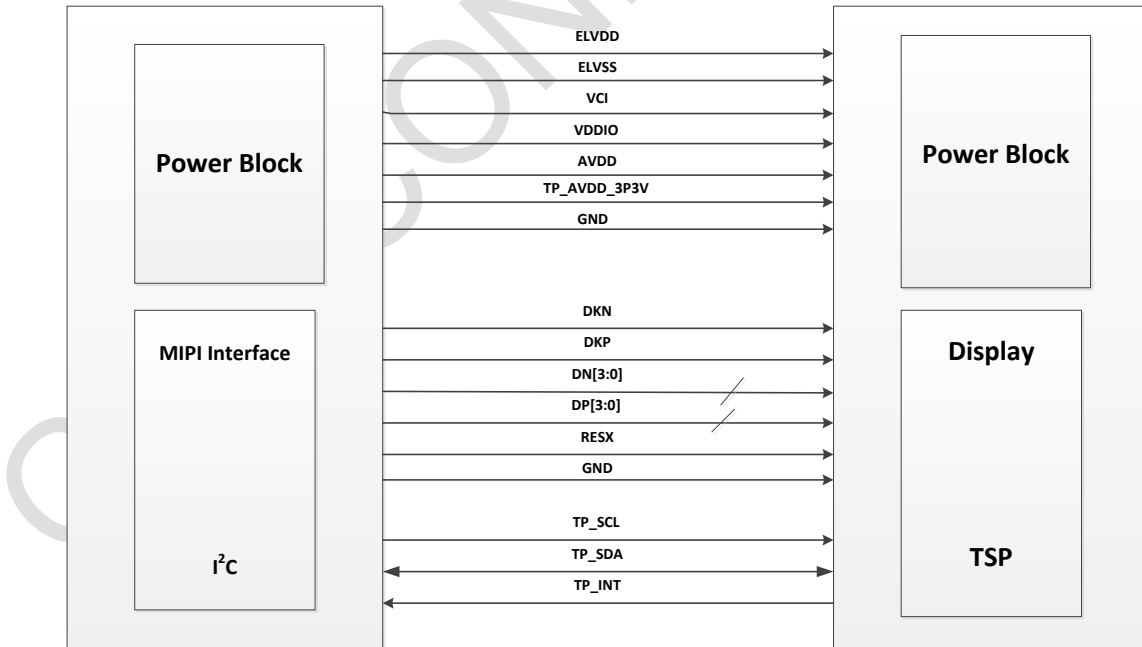
27	GND	GND	Ground
28	RESX	I	This signal will reset the device and should be applied to properly initialize the chip. Signal is active low.
29	VDDIO	POWER	Power supply for driver IC logic circuit.
30	VCI	POWER	Power supply for driver IC analog circuit.
31	NC	NC	Not Connected
32	GND	GND	Ground
33	TP_AVDD_3P3V	POWER	TP power supply input.
34	TP_DVDD_1P8V	POWER	TP power supply for all GPIO pins. Do not connect if it is not used.
35	TP_SDA	I/O	Touch panel I2C data.
36	TP_SCL	I/O	Touch panel I2C clock.
37	TP_RESET	I	Touch panel reset.
38	TP_INT	O	Touch panel interrupt output.
39	GND	GND	Ground

Note: I=Input; O=Output; P=Power; I/O=Input / Output.

### 2.2 Circuit block diagram (Display)



### 2.3 MCU and Display Module Interface Configuration







### 3 Absolute Maximum Ratings

#### 3.1 Driving AMOLED Panel

Maximum Ratings (Voltage Referenced to VSS) Vss=0V, Ta=25°C

Item	Symbol	MIN	MAX	Unit
Analog Power supply	VCI	-0.3	+5.0	V
Logic Power supply	VDDIO	-0.3	+4.0	V
Power IC Power Supply	VBAT	-	+4.5	V
D0P, D0N D1P, D1N D2P, D2N D3P, D3N DKP, DKN	Differential Input	-0.3	+2.5	V
Touch analog power supply	TP_AVDD_3P3V	-0.3	+4.0	V
Touch IC input current at any pin		—	±100	mA

Note: Functional operation should satisfy the limits in the Electrical Characteristics tables or Pin Description section. If the module exceeds the absolute maximum ratings, permanent damage may occur. Besides, if the module is operated with the absolute maximum ratings for a long time, the reliability may also drop.

### 4 Electrical Characteristics

#### 4.1 Driving AMOLED Panel

Ta=25°C

Item	Symbol	MIN	TYP	MAX	Unit	
Logic Power supply	VDDIO	1.65	1.80	3.30	V	
Analog Power supply	VCI	2.65	2.80	3.60	V	
Power IC Power Supply	VBAT	2.90	3.70	4.50	V	
Touch analog power supply	TP_AVDD_3P3V	2.70	2.80	3.60	V	
Input Signal Voltage	High Level	VIH	0.80*VDDIO	-	VDDIO	V
	Low Level	VIL	0.00	-	0.20*VDDIO	V
Output Signal Voltage	High Level	VOH	0.80*VDDIO	-	VDDIO	V
	Low Level	VOL	0.00	-	0.20*VDDIO	V



#### 4.2 Current Consumption

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Panel Power		$P_{NL}$	$V_{CI}=2.8V$	/	1500	/	mW	Note1
IC	Normal	$I_{VCI}$	$V_{DDIO}=1.8V$	/	54	56	mA	Note2
		$I_{VDDIO}$	$V_{BAT}=3.7V$	/	0.02	0.04	mA	
	Stand-by	$I_{VCI}$	$V_{CI}=2.8V$	/	20	70	uA	
		$I_{VDDIO}$	$V_{DDIO}=1.8V$ $V_{BAT}=3.7V$	/	5	10	uA	

Note1: Based on L255 (350) full white pattern.

$$P_{NL} = (ELVDD + |ELVSS|) * I_{ELVDD} + P_{VCI} + P_{VDDIO}$$

Note2: Video Mode 60Hz.

### 5 AC Characteristics

#### 5.1 Input Timing

Table 5-1 Input Timing

Resolution		720RGB X 1280			Unit	Note
Input Timing	Symbol	Min.	Typ.	Max.		
PCLK Frequency	-	57.7	63.2	132.1	MHz	-
Horizontal Active Area	THA	-	720	-	PCLK	-
Horizontal Back Porch	THB	10	16	255	PCLK	-
Horizontal Front Porch	THF	10	16	255	PCLK	-
Horizontal Total	THT	740	784	1230	PCLK	-
Vertical Active Area	TVA	-	1280	-	THT	-
Vertical Back Porch	TVB	10	16	255	THT	-
Vertical Front Porch	TVF	10	16	255	THT	-
Vertical Total	TVT	1300	1344	1790	THT	-
Vertical Frequency	-	-	60	-	Hz	-

#### 5.2 MIPI Interface Characteristics

##### 5.2.1 General Description

The communication can be separated 2 different levels between the MCU and the display module:

- Interface Level: Low level communication
- Packet Level: High level communication

##### 5.2.2 Interface Level Communication

The display module uses data and clock lane differential pairs for DSI. Both clock lane and data lane0 can be driven in Low Power (LP) or High Speed (HS) mode. Data lane1~3 can be driven in

High Speed mode only.

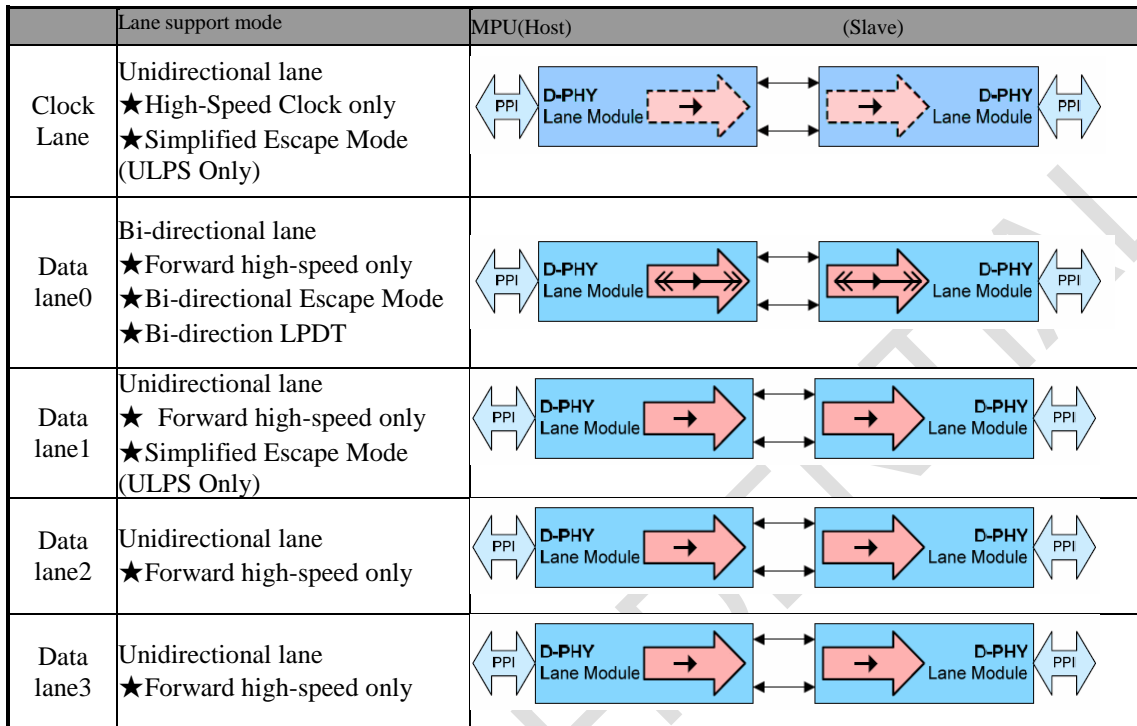


Figure 5-1 Lane types and support mode

The State Codes of the High Speed (HS) and Low Power (LP) lane pair are defined below.

Lane Pair State Code	Line DC Voltage Levels		High Speed (HS)	Low-Power (LP)	
	Dn+ Line	Dn- Line	Burst Mode	Control Mode	Escape Mode
HS-0	Low (HS)	High (HS)	Differential-0	Note 1	Note 1
HS-1	High (HS)	Low (HS)	Differential-1	Note 1	Note 1
LP-00	Low (LP)	Low (LP)	Not Defined	Bridge	Space
LP-01	Low (LP)	High (LP)	Not Defined	HS-Request	Mark-0
LP-10	High (LP)	Low (LP)	Not Defined	LP-Request	Mark-1
LP-11	High (LP)	High (LP)	Not Defined	Stop	Note 2

Figure 5-2 High Speed and Low-Power Lane Pair State Descriptions

### 5.2.3 DSI-CLK Lanes

DSI-CLK+/- lanes can be driven into three different power modes: Low Power Mode (LPM LP-11), Ultra Low Power Mode (ULPM) or High Speed Clock Mode (HSCM).

Clock lanes are in a single end mode (LP=Low Power) when there is entering or leaving Low Power Mode (LPM) or Ultra Low Power Mode (ULPM).

Clock lanes are in the single end mode (LP=Low Power) when there is entering in or leaving out High Speed Clock Mode (HSCM). These entering and leaving protocols are using clock lanes in the single end mode to generate an entering or leaving sequences. The principal flow chart of the different clock lanes power modes is illustrated below.

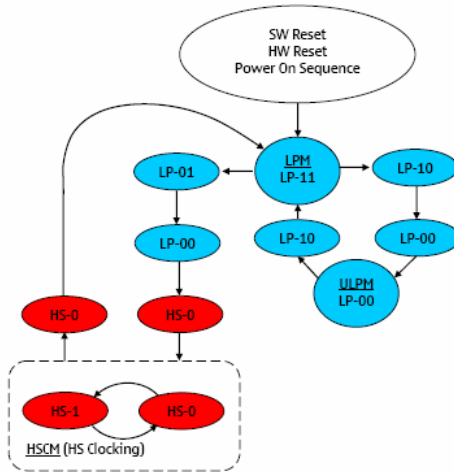


Figure 5-3 Clock Lanes Power Modes

Notes:

1. Low-Power Receivers (LP-Rx) of the lane pair are checking the LP-00 state code, when the Lane Pair is in the High Speed (HS) mode.
2. If Low-Power Receivers (LP-Rx) of the lane pair recognizes LP-11 state code, the lane pair returns to LP-11 of the Control Mode.

5.2.4 DSI Data Lanes

DSI-Dn+/- Data Lanes can be driven in different modes which are:

- Escape Mode (only support DSI\_D0 data lane pair)
- High-Speed Data Transmission (support all data lane pairs)
- Bus Turnaround Request (only support DSI\_D0 data lane pair)

These modes and their entering codes are defined on the following table.

Table 5-2 Entering and leaving sequences

	Entering Mode Sequence	Leaving Mode Sequence
Escape Mode	LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00	LP-00 =>LP-10 =>LP-11 (Mark-1)
High-Speed Data Transmission	LP-11 =>LP-01 =>LP-00 =>HS-0	(HS-0 or HS-1) =>LP-11
Bus Turnaround Request	LP-11 =>LP-10 =>LP-00 =>LP-10 =>LP-00	High-Z, Note

5.2.5 Packet Level Communication

5.2.5.1 Short Packet (SPa) and Long Packet (LPa) Structures

Short Packet (SPa) and Long Packet (LPa) are always used when data transmission is done in Low Power Data Transmission (LPDT) or High-Speed Data Transmission (HSMT) modes.

The type (SPa or LPa) of the packet can be recognized from their package headers (PH).

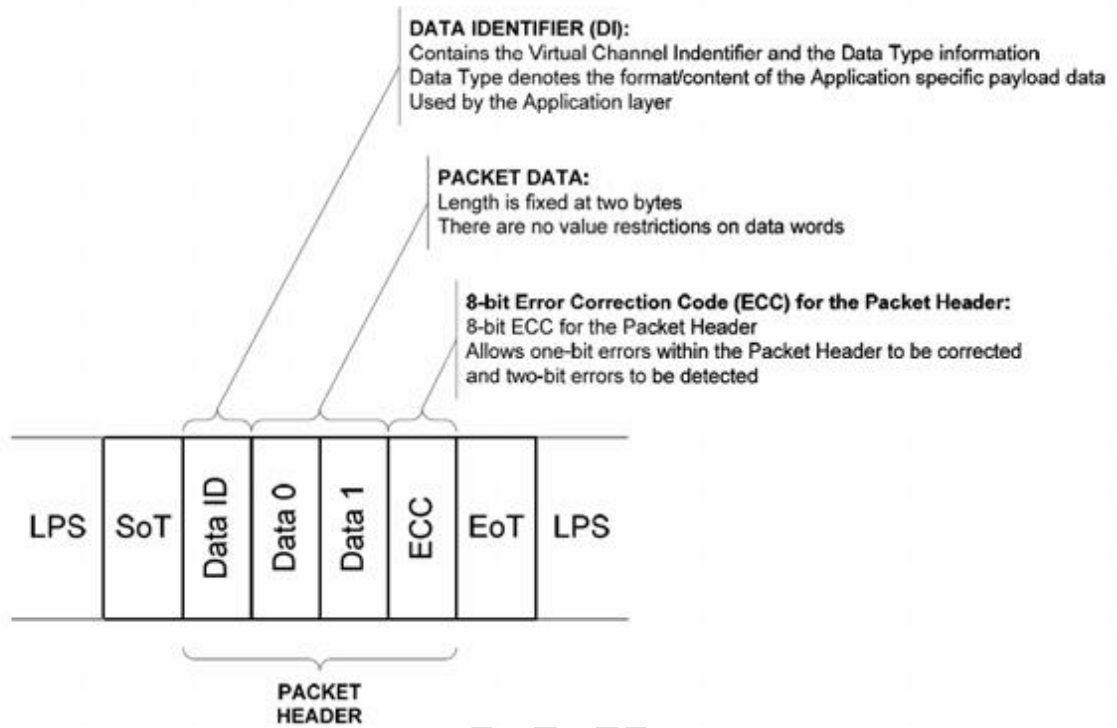


Figure 5-4 Short packet structure

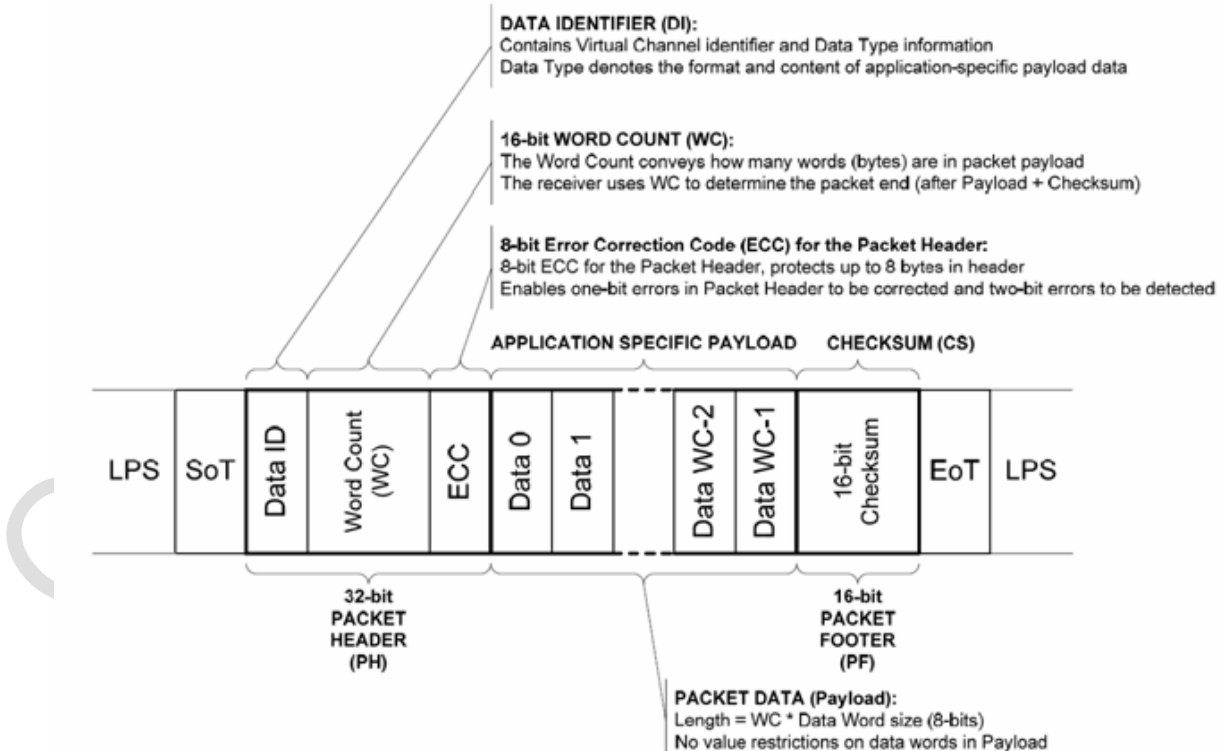


Figure 5-5 Long packet structure

### 5.2.5.2 Packet Transmissions

#### Packet from the MCU to the display module

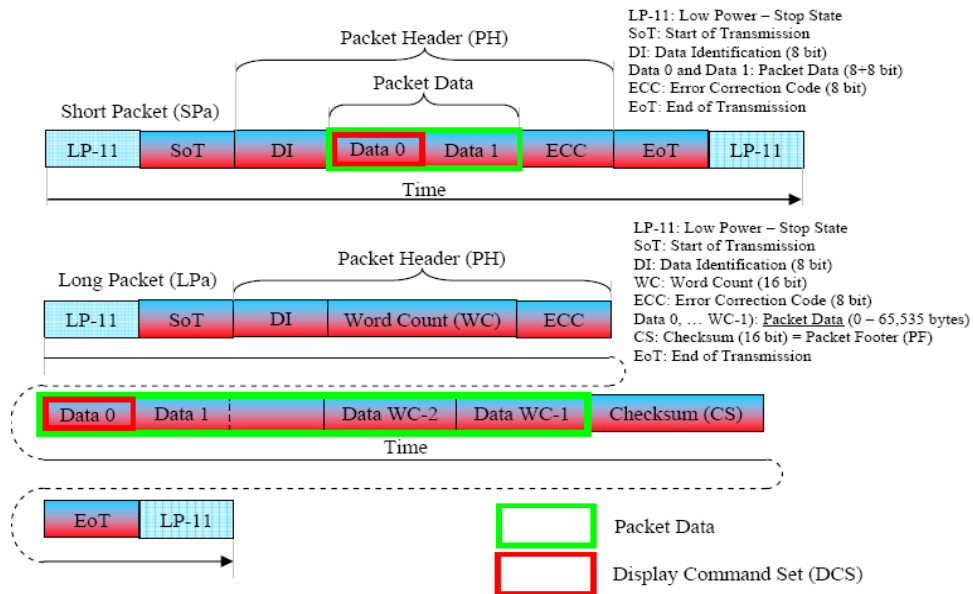


Figure 5-6 DCS on the short packet and long packet

#### Packet from the display module to the MCU

##### Used packet types

The display module is always using Short Packet (SPa) or Long Packet (LPa), when it is returning information to the MCU after the MCU has requested information from the Display Module. This information can be a response of the Display Command Set (DCS).

The used packet type is defined on Data Type (DT).

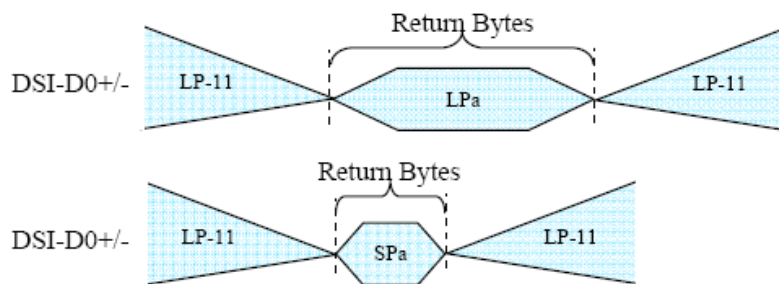


Figure 5-7 Return bytes on single packet

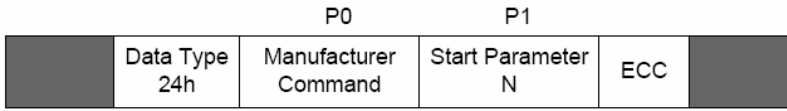
### 5.2.6 Customer-defined Generic Read Data Type Format

The short packet of Data Type 24h (Generic READ, 2 parameters) specifies the register content for read and the nth parameter that will begin reading. After Data Type 24h is received, BTA



is executed. Then, the Nth parameter becomes the first data, and the number of data of WC (word count) value is output.

Packet Structure (processor → peripheral)



Low Power Data Transfer (peripheral → processor)

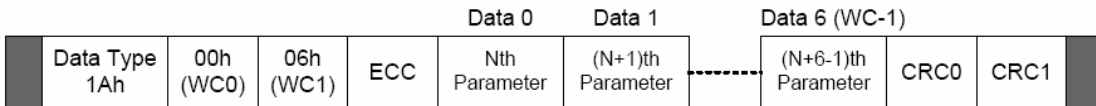
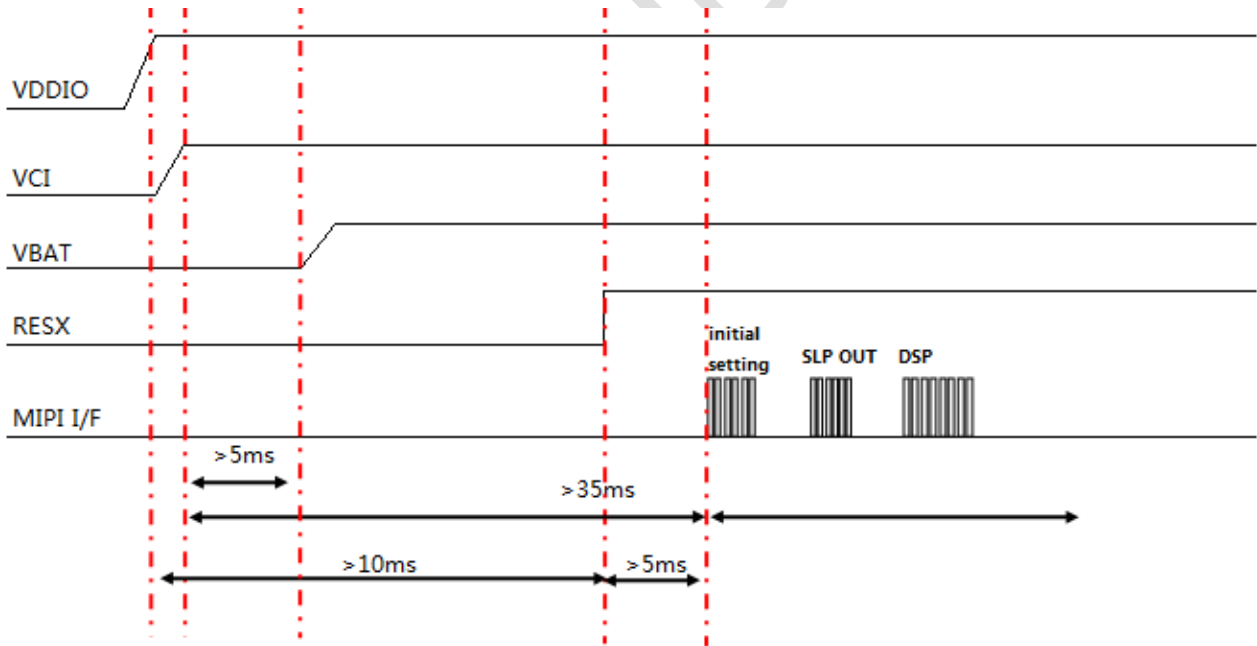


Figure 5-8 Generic read data type format

## 6 Recommended Operating Sequence

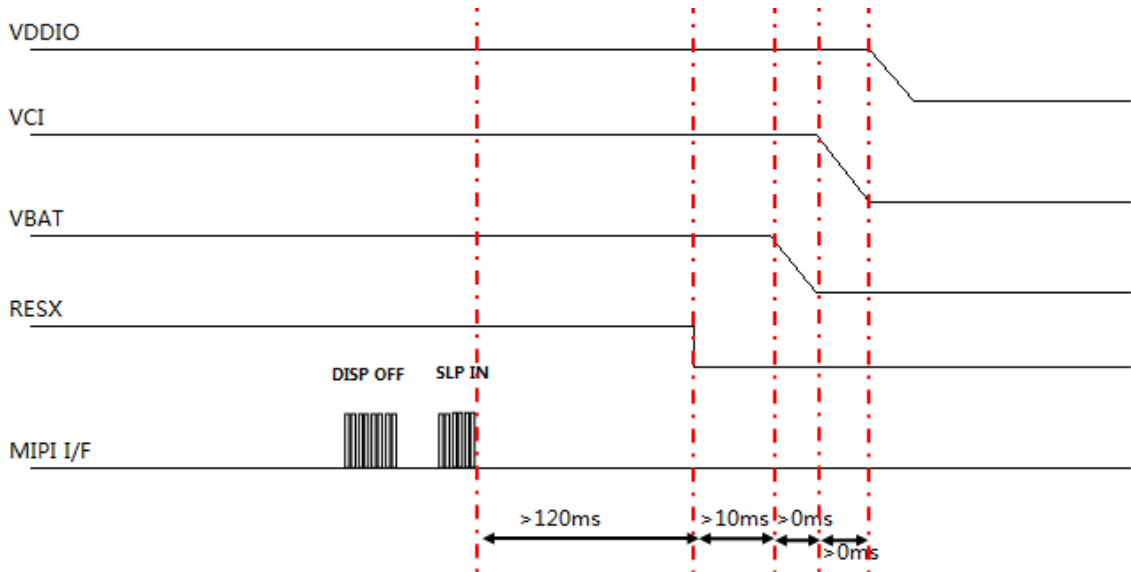
### 6.1 Display Power on / off Sequence

#### 6.1.1 Power On Sequence



Note : VBAT is the power of power IC(for ELVDD & ELVSS & AVDD).

### 6.1.2 Power Off Sequence



### 6.2 Display Initial code

step	Instruction/ Parameter	Delay times	R/W	mipi data type	address		data
					mipi	others	
1	code1		w	0x39	F0	F000	55
						F001	AA
						F002	52
						F003	08
						F004	00
2	code2		w	0x39	C0	C000	C7
						C001	00
						C002	0
						C003	0
						C004	1E
						C005	10
						C006	60
3	code3		w	0x39	C1	C100	C0
						C101	1
						C102	0





						C103	0
						C104	1D
						C105	0
						C106	F0
						C107	C8
3	code4		w	0x39	C2	C200	C0
						C201	2
						C202	0
						C203	0
						C204	1D
						C205	2A
						C206	A0
						C207	9F
3	code5		w	0x39	C3	C300	C0
						C301	2
						C302	0
						C303	0
						C304	1E
						C305	2A
						C306	A0
						C307	9F
3	code6		w	0x39	C4	C400	C0
						C401	2
						C402	0
						C403	0
						C404	1D
						C405	10
						C406	80
						C407	B8
3	code7		w	0x39	C5	C500	C0
						C501	2
						C502	0
						C503	0
						C504	1E



						C505	10
						C506	A0
						C507	B8
3	code8		w	0x39	C6	C600	C7
						C601	0
						C602	2
						C603	0
						C604	1E
						C605	10
						C606	A0
						C607	EC
3	code9		w	0x39	C7	C700	C7
						C701	0
						C702	0
						C703	0
						C704	1F
						C705	10
						C706	60
						C707	E5
4	code10		w	0x39	C8	C800	FF
5	code11		w	0x39	B0	B000	00
						B001	08
						B002	0C
						B003	14
						B004	14
	code12		W	0x39	BA	BA00	20
6	code13		w	0x39	BB	BB00	55
						BB01	55
						BB02	55
						BB03	55
						BB04	55
						BB05	55
						BB06	55
1	code14		w	0x39	F0	F000	55

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						F001	AA
						F002	52
						F003	08
						F004	02
	code14a		w	0x39	E1	E100	00
	code15		w	0x39	CA	CA00	04
	code16		w	0x39	E2	E200	0A
	code17		w	0x39	E3	E300	00
	code18		w	0x39	E7	E700	00
7	code19		w	0x39	ED	ED00	48
						ED01	0
						ED02	E0
						ED03	13
						ED04	8
						ED05	0
						ED06	92
						ED07	8
	code20		W	0x39	FD	FD00	0
						FD01	8
						FD02	1C
						FD03	0
						FD04	0
						FD05	1
8	code21		w	0x39	C3	C300	11
						C301	24
						C302	4
						C303	0A
						C304	1
						C305	4
						C306	0
						C307	1C
						C308	10
						C309	F0
						C30A	0

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						EA00	7F
						EA01	20
	code22		w	0x39	EA	EA02	0
						EA03	0
						EA04	0
1						F000	55
	code23		w	0x39	F0	F001	AA
						F002	52
						F003	08
						F004	01
						B000	1
	code24		w	0x39	B0	B001	1
						B002	1
						B100	5
	code25		w	0x39	B1	B101	5
						B102	5
						B200	D0
	code26		w	0x39	B2	B201	D0
						B202	D0
						B400	37
	code27		w	0x39	B4	B401	37
						B402	37
						B500	5
	code28		w	0x39	B5	B501	5
						B502	5
						B600	54
	code29		w	0x39	B6	B601	54
						B602	54
						B700	24
	code30		w	0x39	B7	B701	24
						B702	24
						B800	24
	code31		w	0x39	B8	B801	24
						B802	24



	code32		w	0x39	B9	B900	14
						B901	14
						B902	14
	code33		w	0x39	BA	BA00	14
						BA01	14
						BA02	14
	code34		w	0x39	BC	BC00	0
						BC01	F8
						BC02	B2
	code35		w	0x39	BE	BE00	23
						BE01	0
						BE02	90
	code36		w	0x39	CA	CA00	80
8	code37		w	0x39	CB	CB00	0
						CB01	0
						CB02	0
						CB03	0
						CB04	0
						CB05	0
						CB06	0
						CB07	0
						CB08	0
						CB09	0
						CB0A	0
						CB0B	0
9	code38		w	0x39	CC	CC00	19
						CC01	19
						CC02	19
						CC03	19
						CC04	19
						CC05	19
						CC06	19
						CC07	19
						CC08	19



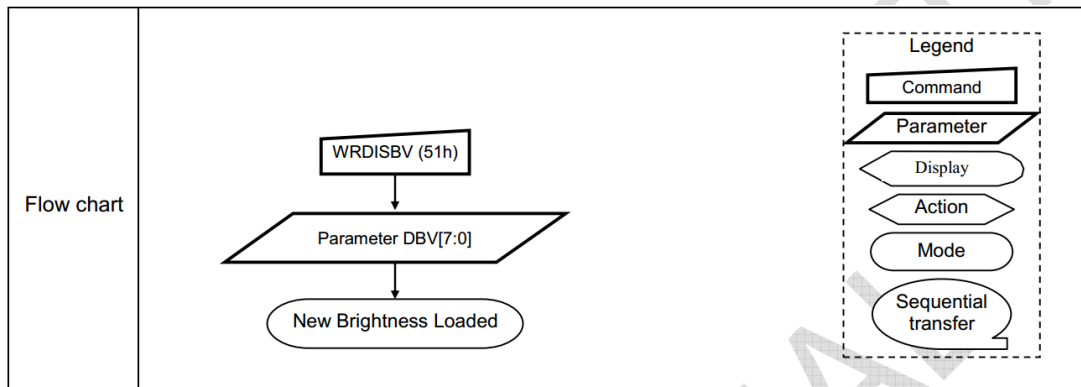
						CC09	19
						CC0A	19
						CC0B	19
1	code39		w	0x39	F0	F000	55
						F001	AA
						F002	52
						F003	08
						F004	03
1	code40		w	0x39	F1	F100	10
						F101	0
						F102	0
						F103	00
						F104	01
						F105	30
	code41		W	0x39	F6	F600	0A
1	code42		w	0x39	F0	F000	55
						F001	AA
						F002	52
						F003	08
						F004	05
1	code43		w	0x39	C0	C000	6
						C001	2
						C002	2
						C003	22
						C004	00
						C005	00
						C006	01
13	code44		w	0x39	35	3500	0
14			w	0x39	11		
15	delay(ms)	100					
16	display on		w	0x39	29		

### 6.3 Brightness control

Use “command 5100h, data xxh” to adjust the Manual Brightness value of the display:

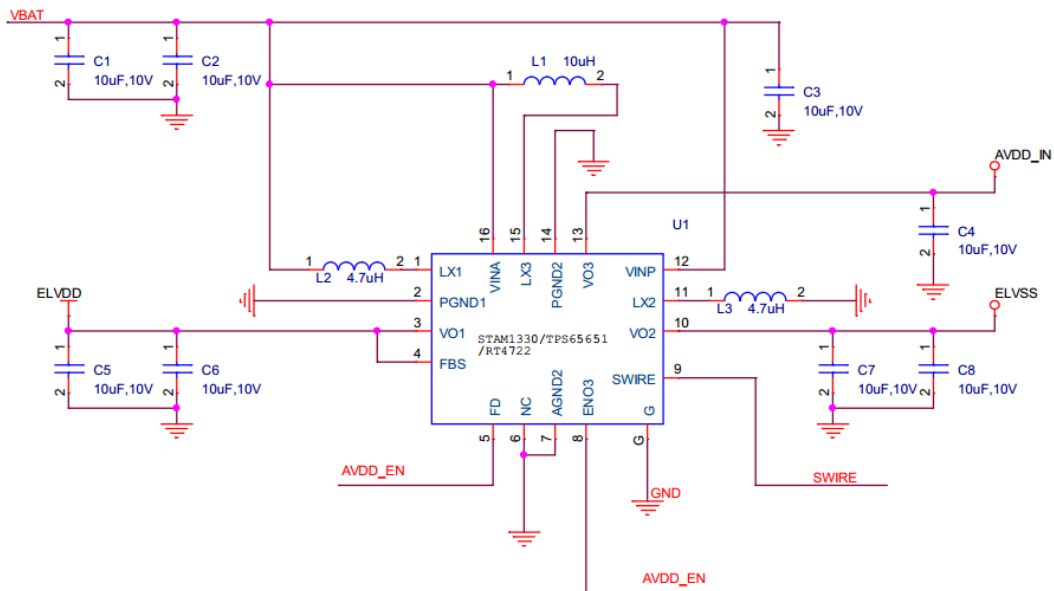
In principle relationship is that 00h value means the lowest brightness and FFh value means the highest brightness.

Inst/Para	R/W	WRDISBV											
		Address		D15-8	D7	D6	D5	D4	D3	D2	D1	D0	HEX
		MIPI	Other										
WRDISBV	W	51h	5100h	x	DBV7	DBV6	DBV5	DBV4	DBV3	DBV2	DBV1	DBV0	FF



## 7 Application Circuit

Concerning ELVDD&ELVSS & AVDD power supply schematic, the Triple DC/DC converter STAM1330/TPS65651/RT4722 is recommended. The application schematics and external components are as below.





Description	Part Reference	Manufacturer	Manufacturer PN
10uF, 10V, ±20%, X5R, 0402	C1 C2 C3 C4 C5 C6 C7 C8	Murata	GRM155R61A106ME44D
		Samsung	CL05A106MP5NUNC
Power Inductor, 10uH, 20%, LS2520	L1	成育科技	ACDNR252010UP-100MT
		科明电子	KMPHS252010-100M
Power Inductor, 4.7uH, 20%, LS2520	L2 L3	成育科技	ACDMR252010T-4R7MT
		科明电子	KMPHS252010-4R7M
QFN16 ( 3.0x3.0 )	U1	TI	TPS65651
		ST	STAM1330
		RICHTEK	RT4722

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## 8 Optical Characteristics Optical Specification

Item	Symbol	Condition	Min	Typ	Max	Unit	Remark
View Angle	$\theta T$	CR $\geq$ 10	80	88		Degree	Note 2 Test Equipment: CS2000A
	$\theta B$		80	88			
	$\theta L$		80	88			
	$\theta R$		80	88			
Contrast Ratio	CR	$\theta=0^\circ$	10000				Note1 Note3 Test Equipment: CS2000A
Response Time	T <sub>ON</sub>	25°C			1	ms	Note1 Note4 Test Equipment: Admesy MSE
	T <sub>OFF</sub>						
Chromaticity	White	x	(0.270)	(0.300)	(0.330)	Test Equipment: CS2000A Note: Chromaticity can be modified according to customer demand	
		y	(0.285)	(0.315)	(0.345)		
	Red	x	(0.630)	(0.670)	(0.710)		
		y	(0.290)	(0.330)	(0.370)		
	Green	x	(0.200)	(0.250)	(0.300)		
		y	(0.660)	(0.710)	(0.760)		
	Blue	x	(0.110)	(0.140)	(0.170)		
		y	(0.030)	(0.060)	(0.090)		
Uniformity	U		75	80		%	Note1 Note6 luminance of center point is 350 $\pm$ 50nits Test Equipment: CS2000A
NTSC			85	100		%	Note5
Luminance	L		300	350	400	Cd/m <sup>2</sup>	Note1 Note7 Test Equipment: CS2000A
Cross-talk					3	%	Note8 L $\leq$ 350nits Test Equipment:

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							CS2000A
Gamma			1.9	2.2	2.5		Gamma=2.2±0.3 (L≤350nits) ; Gamma Self-adjustment (L>350nits) Test Equipment : CS2000A

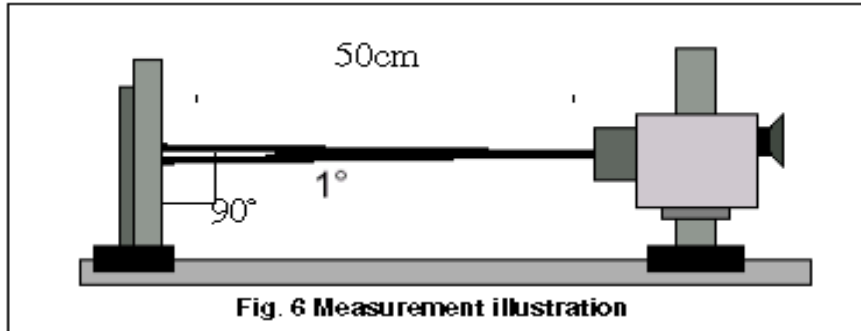
Test Conditions:

1. the ambient temperature is 25°C.
2. The test systems refer to Note1 and Note2.

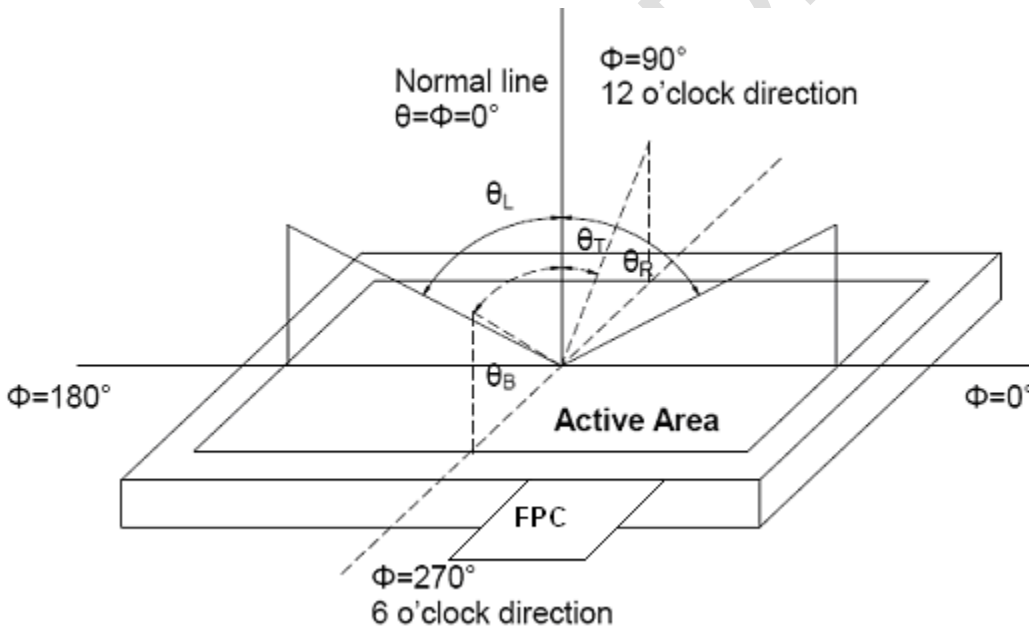
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Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. The optical properties are measured at the center point of the AMOLED screen. All input terminals AMOLED panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system.



Note 3: Definition of contrast ratio

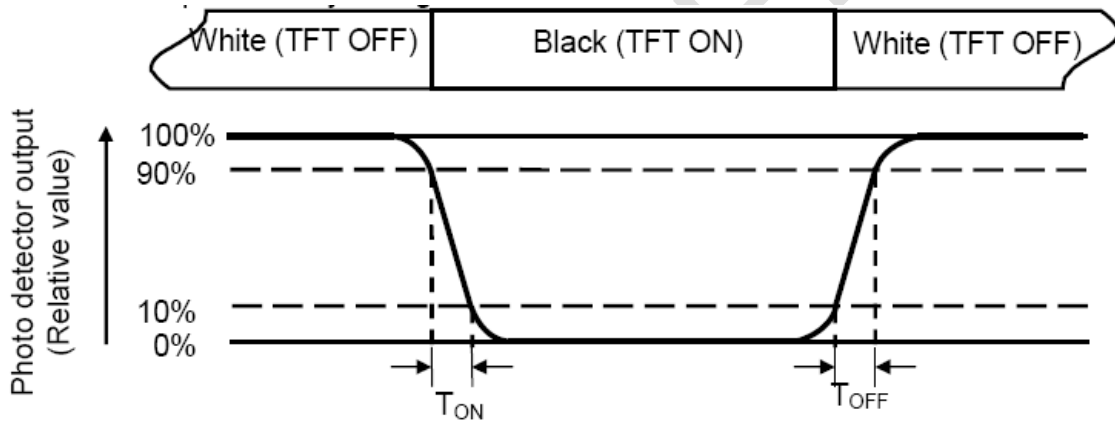
$$\text{Contrast ratio(CR)} = \frac{\text{Luminance measured when LCD is on the "white" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

“White state “: A state where the AMOLED should be driven by V<sub>white</sub>.

“Black state”: A state where the AMOLED should be driven by V<sub>black</sub>.

Note 4: Definition of response time

The response time is defined as the AMOLED optical switching time interval between “White” state and “Black” state. Rise time (T<sub>ON</sub>) is the time between photo detector output intensity changing from 90% to 10%. And fall time (T<sub>OFF</sub>) is the time between photo detector output intensity changing from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of AMOLED.

Note 6: Definition of luminance uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

$$\text{Luminance Uniformity}(U) = L_{\min} / L_{\max}$$

L-----Active area length W----- Active area width

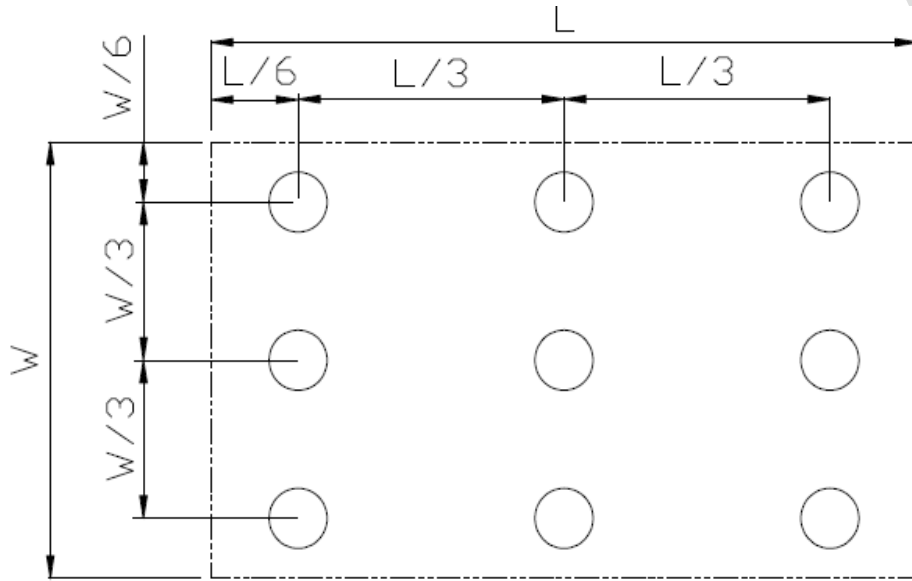


Fig. 2 Definition of uniformity

$L_{\max}$ : The measured maximum luminance of all measurement position.

$L_{\min}$ : The measured minimum luminance of all measurement position.

Note 7: Definition of luminance

Measure the luminance of white state at center point.

Note 8: Cross Talk

A. Measure luminance at the position, P0.

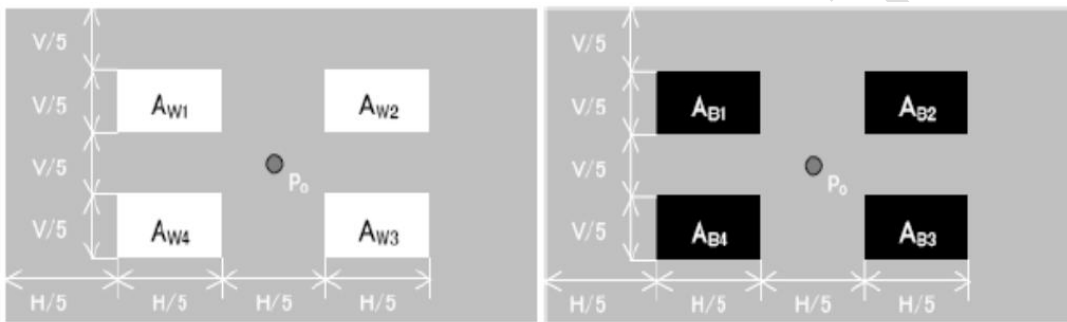
B. Calculate cross talk as below equation.

$$L_{W\_OFF} = \frac{L_{W1} + L_{W2} + L_{W3} + L_{W4}}{4}$$

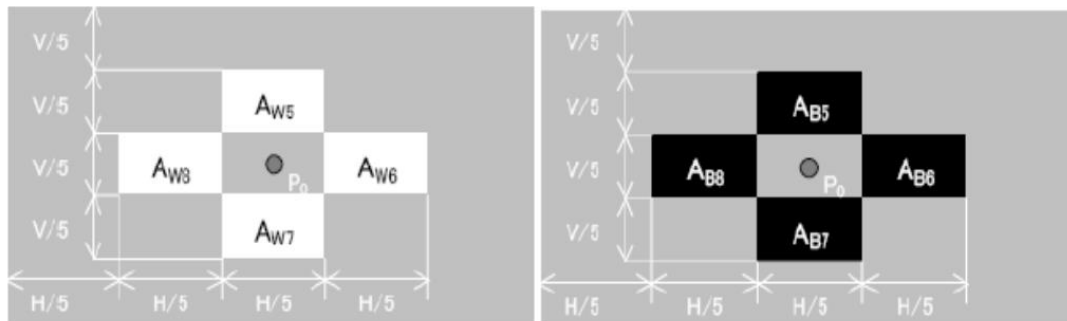
$$L_{B\_OFF} = \frac{L_{B1} + L_{B2} + L_{B3} + L_{B4}}{4}$$

$$\text{crosstalk} = \frac{|L_{Wi\_ON} - L_{W\_OFF}|}{L_{W\_OFF}} \times 100\% \quad (i = 5 \text{ to } 8)$$

$$\text{crosstalk} = \frac{|L_{Bi\_ON} - L_{B\_OFF}|}{L_{B\_OFF}} \times 100\% \quad (i = 5 \text{ to } 8)$$



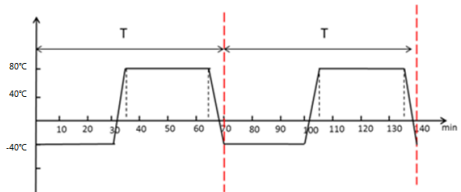
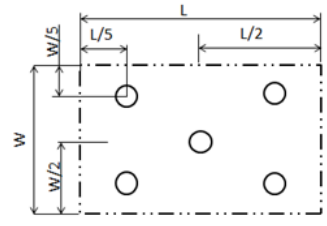
(a)  $L_{W\_OFF}$ ,  $L_{B\_OFF}$  measuring pattern



(b)  $L_{W\_ON}$ ,  $L_{B\_ON}$  measuring pattern



## 9 Environmental / Reliability Test

No	Test Item	Condition	Remark
1	High Temperature Operation	+70°C, 120hrs	IEC60068-2-2,GB2423.2
2	Low Temperature Operation	-20°C, 120hrs	IEC60068-2-1 GB2423.1
3	High Temperature Storage	+80°C, 120hrs	IEC60068-2-2 GB2423.2
4	Low Temperature Storage	-30°C, 120hrs	IEC60068-2-1 GB2423.1
5	High Temperature & High Humidity Operation	60°C, 90% RH,120hrs	IEC60068-2-78 GB/T2423.3
6	Thermal Shock (Non-operation)	-40°C (30 min)~+80°C (30 min), Change time:5min, 30 Cycles 	Start with cold temperature, End with high temperature, IEC60068-2-14,GB2423.22
7	Electro Static Discharge (Operation)	C=150pF, R=330Ω · 5points/panel Air:±8KV, 5times; Contact:±4KV, 5 times; (Environment: 15°C~35°C, 30%~60%, 86Kpa~106Kpa). 	IEC61000-4-2 GB/T17626.2
8	Package Drop Test	1 corner, 3 edges, 6 surfaces Drop height:760mm	IEC60068-2-32 GB/T2423.8
9	Package Vibration Test	Random Vibration: 1.146Grms, 1~200Hz, Random, 30mins/(X, Y, Z)axis	IEC60068-2-34 GB/T2423.11



## 10 Quality Level

### 10.1 AMOLED Module of Characteristic Inspection

The environmental condition and visual inspection shall be conducted as below:

- (1) Ambient temperature:  $22 \pm 3^{\circ}\text{C}$
- (2) Humidity:  $55 \pm 10\% \text{RH}$
- (3) Ambient light intensity of visual inspection: 800 ~ 1200 lux
- (4) Ambient light intensity of function inspection:  $\leq 200 \text{lux}$
- (5) Viewing Distance:  $35 \pm 5 \text{cm}$
- (6) Viewing angle (tolerance): the front side  $90^{\circ} (Z) \pm 30^{\circ}$
- (7) Inspection time:  $10 \pm 2 \text{sec}$

### 10.2 Sampling Procedures for each item acceptance table

Defect type	Sampling Procedures	AQL
Major defect	GB/T2828.1-2003 Inspection level II normal inspection single sample inspection	0.65
Minor defect	GB/T2828.1-2003 Inspection level II normal inspection single sample inspection	1.0

#### Major defect:

Any defect may result in functional failure, or reduce the usability of product for its purpose, such as electrical failure, deformation and etc.

#### Minor defect

A defect does not reduce the usability of product for its intended purpose and un-uniformity, such as dot defect.

The criteria on major and/or minor judgment will be according with the classification of defects.





10.3 Inspection Item

No.	Item	Area	Criterion of Defect			Defect type	
			Type	DS	Acceptable number		
1	Dot defect	AA	Bright Dot	≥10mm	0	Minor	
			Dark Dot	≥10mm	4		
			/				Not allowed
2	No display	AA	/			Major	
3	Abnormal display	AA	/			Major	
4	Normally white	AA	/			Major	
5	Line Defect	AA	single line	Bright line	Not allowed	Major	
				Dark line	Not allowed		
			Multiple lines	Bright line	Not allowed		
				Dark line	Not allowed		
			Half-Line	Bright line	Not allowed		
				Dark line	Not allowed		
6	Edge/Side breakage	OA	The following Criterion is applicable to any side (unit: mm)				Minor
			Z	X	Y	Acceptable number	
			≤ T	≤2.0	not extended to circuit Area or Frit	<5	
7	Glass crack	Whole area	/			Major	
8	Panel scratch	AA	W (mm)	L (mm)	DS (mm)	Acceptable number	Minor
			W≤0.03	L<5.0	≥10	Ignore	
			0.03<W≤0.05	L≤2.0	≥10	Ignore	
				2.0<L≤5.0	≥10	2	
			0.05<W	-	0	0	
	L>5.0	0	0				
9	Frit encapsulation	FA	Frit width can't be less than the design width of 9/10.It should not have bubble or breakage.			Minor	
10	Raised point	AA、OA	/			Major	

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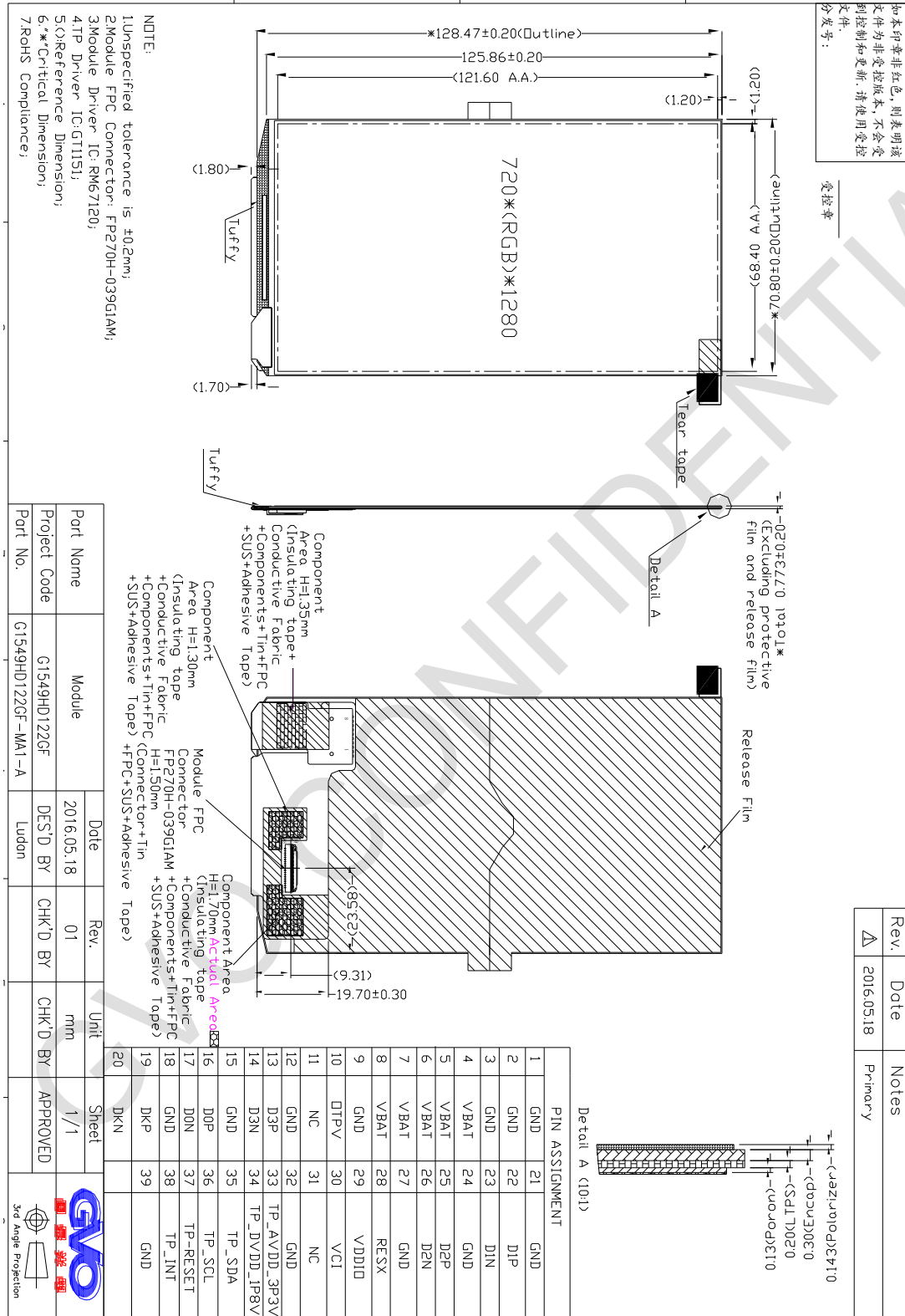
						allowed	
11	Concave dot, Black and white dot, Polarizer Dent/Bubble	AA	Front(Encap surface)	D (mm)	DS (mm)	Acceptable number	Minor
				$D \leq 0.20$	$\geq 10$	Ignore	
				$0.20 < D \leq 0.50$	$\geq 10$	3	
				$0.50 < D$	$\geq 10$	0	
			Rear (LTPS surface)	/	/	Ignore	
12	Polarizer scratch/ Fiber(Linear)	AA	W (mm)	L (mm)	DS	Acceptable number	Minor
			$W \leq 0.03$	Ignore	$\geq 10$	Ignore	
			$0.03 < W \leq 0.05$	$L \leq 2.0$	$\geq 10$	Ignore	
				$2.0 < L \leq 5.0$	$\geq 10$	3	
			$0.05 < W$	-	$\geq 10$	0	
				$L > 5.0$	$\geq 10$	0	
13	Panel dirt	AA	/	/	/	Not allowed	Minor
14	UV	Not IC side	Over coating			Not allowed	Minor
		IC side	The coating of IC side is not higher than POL.				
15	Tuffy glue	IC and FPC bonding area	The coating should not have breakage or Bubble.				Major
			The coating is not higher than POL.				Minor
		Other area	Tuffy glue is not allowed to interrupt and the diameter of Bubble is not more than 0.5mm.				
			The coating is not higher than POL.				
		IC	Not allowed				
	FPC	Ribbon glue: the width is not more than 1mm. Dot glue: the diameter is not more than 2mm.					
16	FPCA	FPC	The component can not reverse polarity.				Major
			No wrong insertion				Major
			FPC should not have serious crease which destroy the line, prick and spots damage. Scratch is not allowed if Cu layer is exposed.				Minor
			The gold fingers should not be oxidized, scraped, folded, impressed, broken, spotted or dissymmetry.				Major
			Make sure FPC is not scalded, with its location holes not having deficiency or obviously shift.				Major
			The component of FPC should be the same as BOM list.				Major
			No remaining soldering Sn				Major
			No visual particle on the pad line				Minor



17	FPCA End Overhang	Bonding area	The size above 1/2 of soldering electrode of the parts overhang to the LAND is prohibited. (Contacting near other components is prohibited)	Major
18	FPCA Tilt Defect	Bonding area	Not allowed	Major
19	Package	other	Products should put into the anti-static trays with non-overlapping and the trays should be staggered placed.	Minor
			Different products cannot be mixed into the same inner package.	
			The package should not have obvious deformation or breakage .The printing labels type and quantity are correct.	
			The package should have QC signature. ROHS label is needed if the product is under ROHS control.	

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# 11 Mechanical Drawing

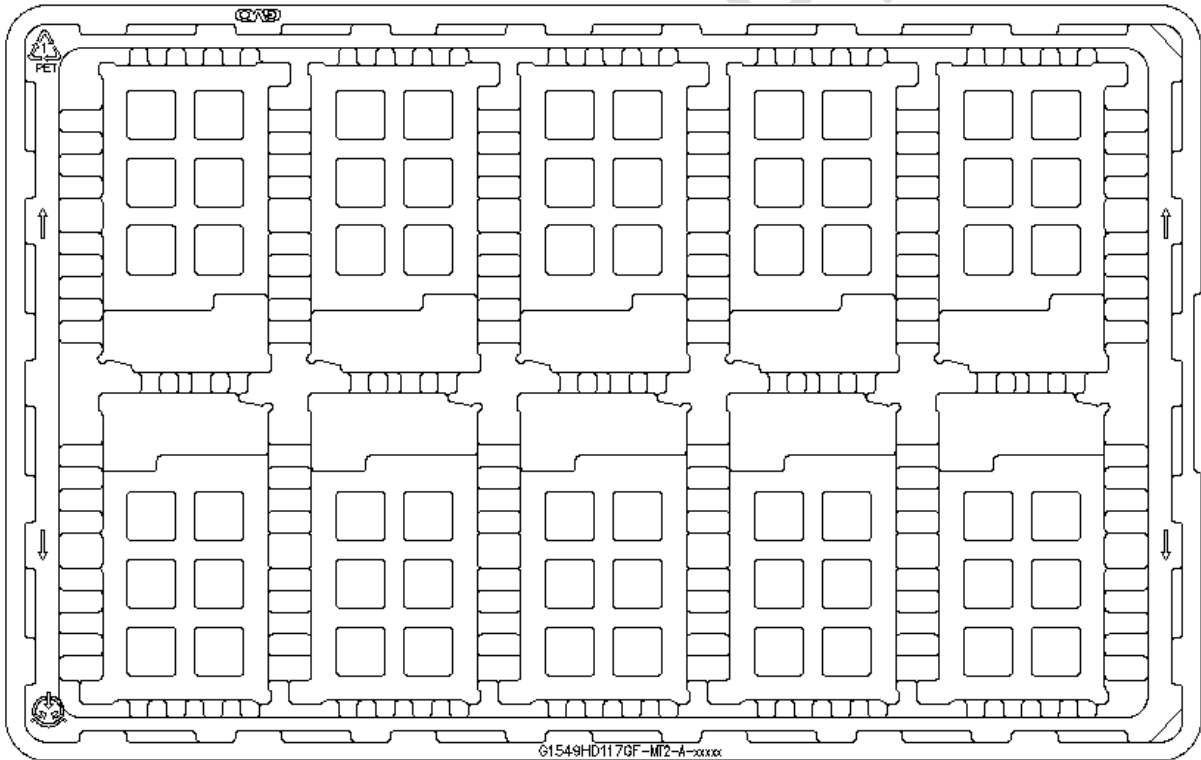


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### Packing Drawing

Packing Condition	Contents
Packing Type	TRAY + Carton packing type
TRAY material model	tray (10 <sup>5</sup> ~10 <sup>9</sup> Ω)
Tray packing type	See the picture 1
Number of panels per tray	10 pieces
Number of Tray per carton	18units (( 17 units + 1 empty)PET tray )
Number of panels per carton	170 pieces



Picture 1



## 12 Precautions for Use of AMOLED Modules

### 12.1 Handling Precautions:

- 12.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from height.
- 12.1.2 Do not press down the screen or the adjoining areas too hard because the color tone may be shifted.
- 12.1.3 The polarizer covering the display surface of the AMOLED module is soft and easily scratched. Handle this polarizer carefully.
- 12.1.4 If the display surface is contaminated, blow on the surface and gently wipe it with a soft dry cloth. If it is still not completely clear, moisten the cloth with ethyl alcohol.
- 12.1.5 Solvents may damage the polarizer. Do not use water, ketone or aromatic solvents except ethyl alcohol.  
Do not attempt to disassemble the AMOLED Module.
- 12.1.6 If the logic circuit power is off, do not apply the input signals.
- 12.1.7 To prevent destruction from static electricity, be careful to maintain an optimum working environment.
- 12.1.8 Be sure to make yourself in contact with the ground when handling with the AMOLED Modules.
- 12.1.9 Tools required for assembly, such as soldering irons, must be properly ground.
- 12.1.10 To reduce the generation of static electricity, do not conduct assembly or other work under dry conditions.
- 12.1.11 To protect the display surface, the AMOLED Module is coated with a film. Be careful when peeling off this protective film, because static electricity may generate.

### 12.2 Storage Precautions:

- 12.2.1 When storing the AMOLED modules, be sure that they are not directly exposed to the sunlight or the light of fluorescent lamps.
- 12.2.2 The AMOLED modules should be stored under the storage temperature range. If the AMOLED modules will be stored for a long time, the recommended condition is:  
Temperature: 0°C~40°C Relatively humidity: ≤80%
- 12.2.3 The AMOLED modules should be stored in the room without acid, alkali or harmful gas.

### 12.3 Transportation Precautions:

- 12.3.1 The AMOLED modules should not be suffered from falling and violent shocking during transportation. Besides, excessive press, water, damp and sunshine, should be avoided.